



40V 175°C P-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

| BV _{DSS} | R _{DS(ON)} max | I _D max T _C = +25°C |
|-------------------|-----------------------------|--|
| -40V | $26m\Omega @ V_{GS} = -10V$ | -50A |

Description and Applications

This MOSFET is designed to minimize the on-state resistance (R_{DS(ON)}) and yet maintain superior switching performance, making it ideal for high-efficiency power management applications.

- Motor Control
- Backlighting
- DC-DC Converters
- Printer Equipment

Features

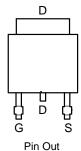
- Rated to +175°C Ideal for High Ambient Temperature Environments
- 100% Unclamped Inductive Switch (UIS) Test in Production
- Low On-Resistance
- Fast Switching Speed
- Low Input/Output Leakage
- Lead-Free Finish; RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability
- An Automotive-Compliant Part is Available Under Separate Datasheet (DMPH4023SK3Q)

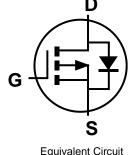
Mechanical Data

- Case: TO252 (DPAK)
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: See Diagram
- Terminals: Finish Matte Tin Finish Annealed over Copper Leadframe. Solderable per MIL-STD-202, Method 208 (3)
- Weight: 0.33 grams (Approximate)



Top View





Ordering Information (Note 4)

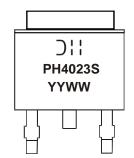
| Part Number | Case | Packaging |
|----------------|--------------|-------------------|
| DMPH4023SK3-13 | TO252 (DPAK) | 2,500/Tape & Reel |

Top View

Notes:

- 1. EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. All applicable RoHS exemptions applied.
- See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

Marking Information



DII = Manufacturer's Marking
PH4023S = Product Type Marking Code
YYWW = Date Code Marking
YY = Last Two Digits of Year (ex: 17 = 2017)
WW = Week Code (01 to 53)



Maximum Ratings ($@T_A = +25^{\circ}C$, unless otherwise specified.)

| Characteristic | Symbol | Value | Unit | |
|--|-----------------|-----------------|------------|----|
| Drain-Source Voltage | V_{DSS} | -40 | V | |
| Gate-Source Voltage | V_{GSS} | ±20 | V | |
| Continuous Drain Current (Note 6) $V_{GS} = -10V$ $T_C = +25^{\circ}C$ $T_C = +100^{\circ}C$ | | l _D | -50 -35 | А |
| Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%) | | I _{DM} | -70 | Α |
| Maximum Continuous Body Diode Forward Current (Note 6) | | Is | -4 | Α |
| Pulsed Body Diode Forward Current (10µs Pulse, Duty Cycle = 1%) | | I _{SM} | -70 | А |
| Avalanche Current, L = 0.1mH (Note 7) | I _{AS} | -40 | А | |
| Avalanche Energy, L = 0.1mH (Note 7) | | Eas | 85 | mJ |

Thermal Characteristics (@TA = +25°C, unless otherwise specified.)

| Characteristic | Symbol | Value | Unit | |
|--|--------------|----------------------------------|-------------|------|
| Total Power Dissipation (Note 5) | | P_{D} | 2.1 | W |
| Thermal Resistance, Junction to Ambient (Note 5) | Steady State | $R_{	heta JA}$ | 71 | °C/W |
| Total Power Dissipation (Note 6) | | P _D | 3.6 | W |
| Thermal Resistance, Junction to Ambient (Note 6) Steady State | | $R_{	heta JA}$ | 41 | °C/W |
| Thermal Resistance, Junction to Case | | $R_{\theta JC}$ | 1.5 | C/VV |
| Operating and Storage Temperature Range | | T _{J,} T _{STG} | -55 to +175 | °C |

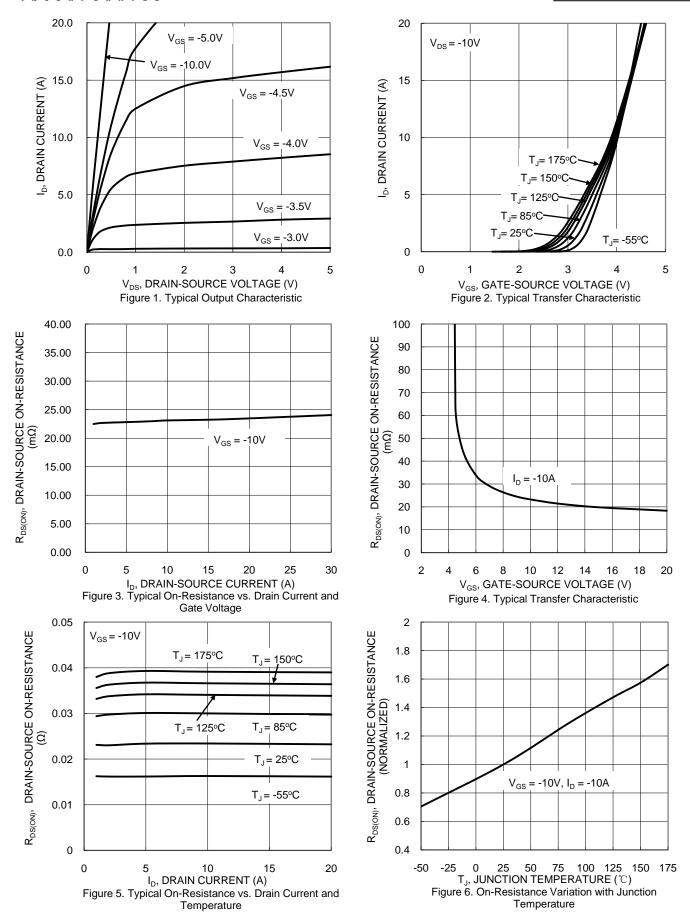
Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

| Characteristic | Symbol | Min | Тур | Max | Unit | Test Condition | |
|-----------------------------------|---------------------|-----|-------|------|----------|--|--|
| OFF CHARACTERISTICS (Note 8) | | | | | | | |
| Drain-Source Breakdown Voltage | BV _{DSS} | -40 | _ | _ | V | $V_{GS} = 0V, I_D = -250\mu A$ | |
| Zero Gate Voltage Drain Current | I _{DSS} | _ | _ | -1 | μA | $V_{DS} = -40V, V_{GS} = 0V$ | |
| Gate-Source Leakage | I _{GSS} | _ | _ | ±100 | nA | $V_{GS} = \pm 20V$, $V_{DS} = 0V$ | |
| ON CHARACTERISTICS (Note 8) | | | | | | | |
| Gate Threshold Voltage | V _{GS(TH)} | -1 | _ | -3 | V | $V_{DS} = V_{GS}, I_{D} = -250 \mu A$ | |
| Static Drain-Source On-Resistance | R _{DS(ON)} | _ | 21 | 26 | mΩ | $V_{GS} = -10V, I_{D} = -10A$ | |
| Diode Forward Voltage | V_{SD} | _ | -0.75 | -1.2 | V | $V_{GS} = 0V$, $I_S = -1A$ | |
| DYNAMIC CHARACTERISTICS (Note 9) | | | | | | | |
| Input Capacitance | C _{iss} | _ | 1091 | _ | pF | \\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\ | |
| Output Capacitance | Coss | _ | 288 | _ | pF | $V_{DS} = -20V, V_{GS} = 0V,$ -f = 1MHz | |
| Reverse Transfer Capacitance | Crss | _ | 111 | _ | pF | 1 – 1101112 | |
| Gate Resistance | R_g | _ | 14 | _ | Ω | $V_{DS} = 0V$, $V_{GS} = 0V$, $f = 1MHz$ | |
| Total Gate Charge | Qg | _ | 18.7 | _ | nC | $V_{DS} = -20V, I_{D} = -10A,$ | |
| Gate-Source Charge | Q _{gs} | _ | 4.2 | _ | nC | , , , | |
| Gate-Drain Charge | Q_{gd} | _ | 5.0 | _ | nC | V _{GS} = -10V | |
| Turn-On Delay Time | t _{D(ON)} | _ | 5.3 | _ | ns | | |
| Turn-On Rise Time | t _R | _ | 4.8 | _ | ns | $V_{DD} = -20V, V_{GS} = -10V,$ | |
| Turn-Off Delay Time | t _{D(OFF)} | _ | 30.7 | _ | ns | $R_G = 6\Omega$, $I_D = -10A$ | |
| Turn-Off Fall Time | t _F | _ | 23.4 | _ | ns | | |
| Reverse Recovery Time | t _{RR} | _ | 17.8 | _ | ns | 1 100 di/dt 1000/::- | |
| Reverse Recovery Charge | Q _{RR} | _ | 9.2 | _ | nC | $I_F = -10A$, di/dt = -100A/ μ s | |

Notes:

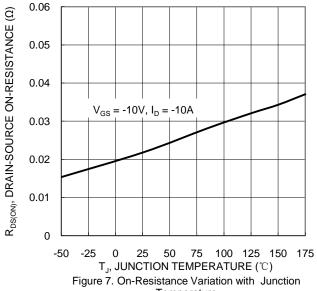
- 5. Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.
 6. Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate.
- 7. I_{AS} and E_{AS} ratings are based on low frequency and duty cycles to keep $T_J = +25^{\circ}C$.
- 8. Short duration pulse test used to minimize self-heating effect.
- 9. Guaranteed by design. Not subject to product testing.



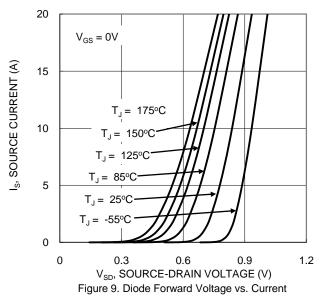


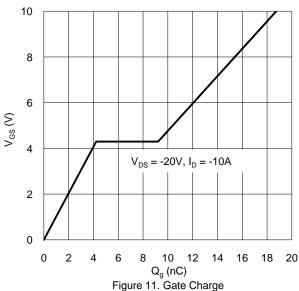






Temperature





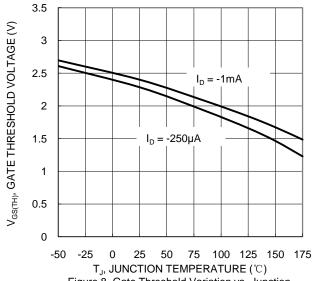
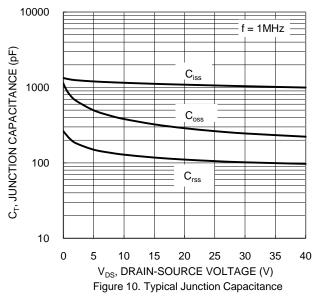
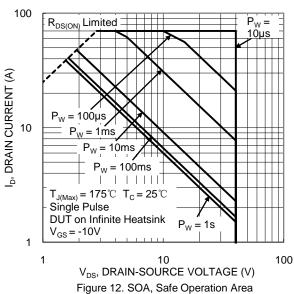


Figure 8. Gate Threshold Variation vs. Junction Temperature







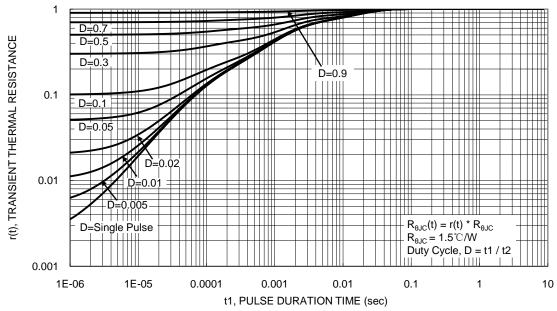


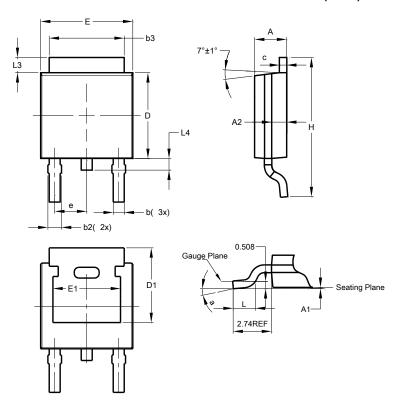
Figure 13. Transient Thermal Resistance



Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

TO252 (DPAK)

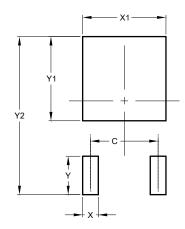


| TO252 (DPAK) | | | | | |
|----------------------|------|-------|-------|--|--|
| Dim | Min | Max | Тур | | |
| Α | 2.19 | 2.39 | 2.29 | | |
| A1 | 0.00 | 0.13 | 0.08 | | |
| A2 | 0.97 | 1.17 | 1.07 | | |
| b | 0.64 | 0.88 | 0.783 | | |
| b2 | 0.76 | 1.14 | 0.95 | | |
| b3 | 5.21 | 5.46 | 5.33 | | |
| С | 0.45 | 0.58 | 0.531 | | |
| D | 6.00 | 6.20 | 6.10 | | |
| D1 | 5.21 | - | - | | |
| е | - | - | 2.286 | | |
| Ε | 6.45 | 6.70 | 6.58 | | |
| E1 | 4.32 | - | - | | |
| Н | 9.40 | 10.41 | 9.91 | | |
| L | 1.40 | 1.78 | 1.59 | | |
| L3 | 0.88 | 1.27 | 1.08 | | |
| L4 | 0.64 | 1.02 | 0.83 | | |
| а | 0° | 10° | - | | |
| All Dimensions in mm | | | | | |

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

TO252 (DPAK)



| Dimensions | Value (in mm) | | |
|------------|---------------|--|--|
| С | 4.572 | | |
| Х | 1.060 | | |
| X1 | 5.632 | | |
| Υ | 2.600 | | |
| Y1 | 5.700 | | |
| Y2 | 10.700 | | |



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